

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	9178	mechanical adj structure	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/07/17 17:00
2	BRS	L2	28	1 and (bonding adj pad)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/07/17 16:57
3	BRS	L3	0	1 and (non-device adj section)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM TDB	2002/07/17 17:01

	Type	Hits	Search Text
1	BRS	0	soft adj curing adj insulating
2	BRS	8	soft near5 curing near5 insulat\$4
3	BRS	1475	thermal\$3 near5 compress\$5 near5 (insulat\$5 or metal)
4	BRS	42	(thermal\$3 near5 compress\$5 near5 (insulat\$5 or metal)) and (cur\$3 near5 insulat\$5)
5	BRS	11	257/750,753,758,765,781,774,508.ccls. and (mechanical adj structure)
6	BRS	0	257/750,753,758,765,781,774,508.ccls. and (non-device adj section)
7	BRS	4431	257/750,753,758,765,781,774,508.ccls.
8	BRS	0	257/750,753,758,765,781,774,508.ccls. and (dummy adj bonding adj pad)
9	BRS	154	257/750,753,758,765,781,774,508.ccls. and dummy

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/16 15:19		
2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/08 13:32		
3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/08 13:40		
4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/08 13:41		
5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/16 15:24		
6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/16 15:30		
7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/16 15:30		
8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/16 15:31		
9	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/16 15:31		